



Statement of Materials, Construction

24L-SOICW -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.14299	Cu	7440-50-8	0.13929	21.69301	97.413
				Fe	7439-89-6	0.00336	0.52332	2.35
				Pb	7439-92-1	0.00004	0.00900	0.03
				P	7723-14-0	0.00012	0.01837	0.0825
				Zn	7440-66-6	0.00018	0.02784	0.125
2	Die	Silicon Chip	0.00888	Si	7440-21-3	0.00884	1.37605	99.5
3	Die attach material	Conductive Epoxy	0.00112	Epoxy resin	Proprietary	0.00017	0.02616	15
				Silver	7440-22-4	0.00089	0.13867	79.5
				Aromatic Amine	Proprietary	0.00006	0.00959	5.5
4	Wire	Gold	0.00074	Au	7440-57-5	0.00074	0.11524	99.99
4	Lead Finish	Alloy	0.00757	Pb	7439-92-1	0.00076	0.11789	10
				Sn	7440-31-5	0.00681	1.06105	90
				Fused Silica	60676-86-0	0.40724	63.42277	84.7
6	Encapsulation	Epoxy Resin	0.4808	Epoxy resin	29690-82-2	0.03125	4.86715	6.5
				Phenol Resin	9003-35-4	0.01923	2.99517	4
				Brominated Epoxy Resin	40039-93-8	0.01202	1.87198	2.5
				Carbon Black	1333-86-4	0.00144	0.22464	0.3
				Antimony trioxide	1309-64-4	0.00962	1.49759	2
Total Package weight			0.64210					

Note: Component Weight based on assembly of generic parts.